






















Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	Solder Resist	0.70mil	4.1
4		Top Layer	Copper	1.38mil	
5		Dielectric 1	1080	2.72mil	3.4
6		plane 1	Copper	1.38mil	
7		Dielectric 2	TU-863	4.00mil	3.7
8		M1	Copper	0.71mil	
9		Dielectric 3	1080	5.58mil	3.4
10		plane 2	Copper	1.38mil	
11		Dielectric 4	TU-863	4.00mil	3.7
12		plane 3	Copper	1.38mil	
13		Dielectric 5	1080	5.58mil	3.4
14		M2	Copper	0.71mil	
15		Dielectric 6	TU-863	4.00mil	3.7
16		plane 4	Copper	1.38mil	
17		Dielectric 7	1080	2.72mil	3.4
18		Bottom Layer	Copper	1.38mil	
19		Bottom Solder	Solder Resist	0.70mil	4.1
20		Bottom Overlay			
21		Bottom Paste			
Height : 39.69mil					